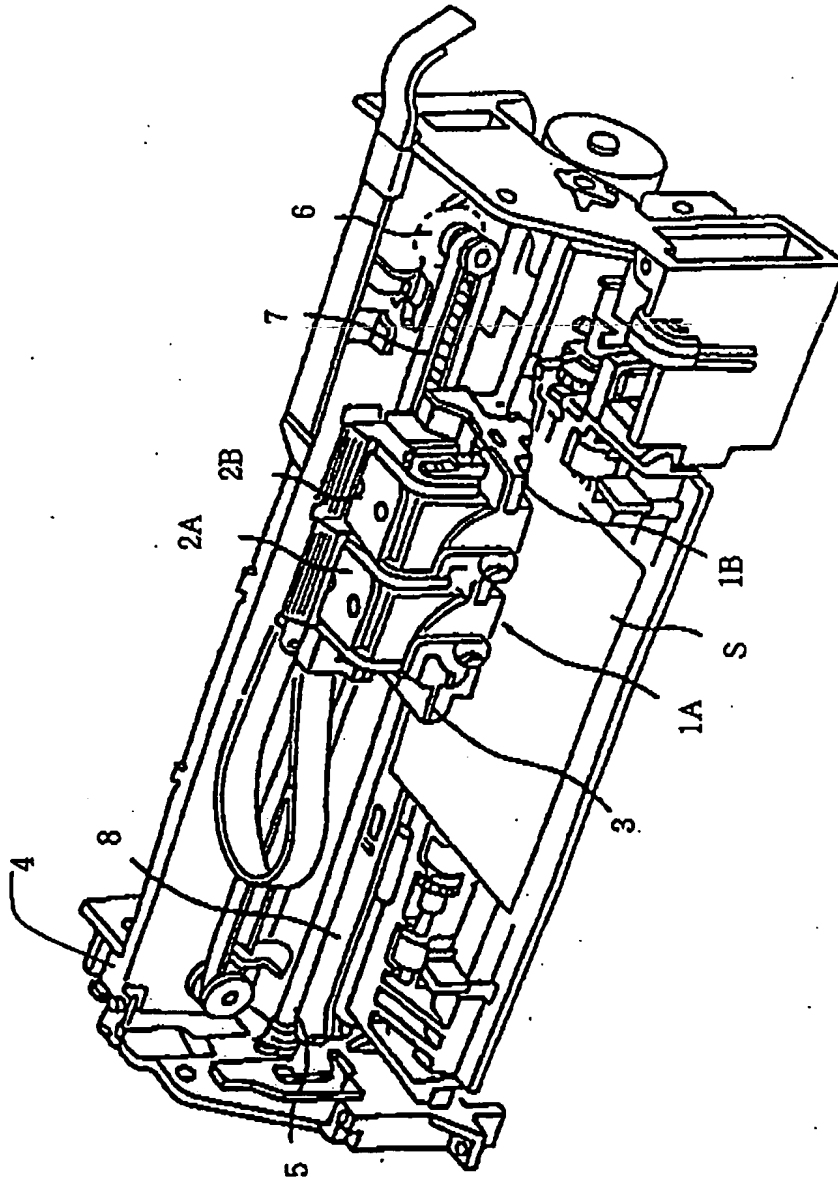


This exploded perspective view illustrates the assembly of a multi-layered electronic component. The assembly includes a base substrate (10) with a top surface (20) and a bottom surface (50). A central layer (12) is positioned above the base, featuring a series of parallel conductive strips (14) and a central rectangular opening (13). A top layer (131) is positioned above the central layer, featuring a series of parallel conductive strips (132) and a central rectangular opening (133). A top cover (130) is positioned above the top layer, featuring a series of parallel conductive strips (134) and a central rectangular opening (135). A central layer (110) is positioned between the top layer and the top cover, featuring a series of parallel conductive strips (111) and a central rectangular opening (112). A bottom layer (30) is positioned below the central layer, featuring a series of parallel conductive strips (31) and a central rectangular opening (32). A bottom cover (300) is positioned below the bottom layer, featuring a series of parallel conductive strips (301) and a central rectangular opening (302). A series of parallel conductive strips (40) are positioned between the top layer and the top cover, featuring a series of parallel conductive strips (41) and a central rectangular opening (42). A series of parallel conductive strips (51) are positioned between the bottom layer and the bottom cover, featuring a series of parallel conductive strips (52) and a central rectangular opening (53). A series of parallel conductive strips (60) are positioned between the central layer and the top cover, featuring a series of parallel conductive strips (61) and a central rectangular opening (62). A series of parallel conductive strips (90) are positioned between the central layer and the bottom cover, featuring a series of parallel conductive strips (91) and a central rectangular opening (92).

[illegible]

FIG.3



A detailed cross-sectional view of a semiconductor device 100. The device features a substrate 10 with a base layer 12. A central region 14 contains a structure 130, which is part of a larger assembly 110. This assembly is surrounded by a layer 140, which is further enclosed by a top layer 141 (160). A central core 33 is visible within the structure 130. Various other layers and components are labeled with numbers, including 131, 132, 133, 134, 142, 143, 150, 160, 180, 20, 21, 30, 31, 36, 37, 40, 41, 42, 50, 51, 60, 70, 80, 90, and 100. The diagram illustrates the complex internal structure and layering of the device.

[illegible]

FIG. 6

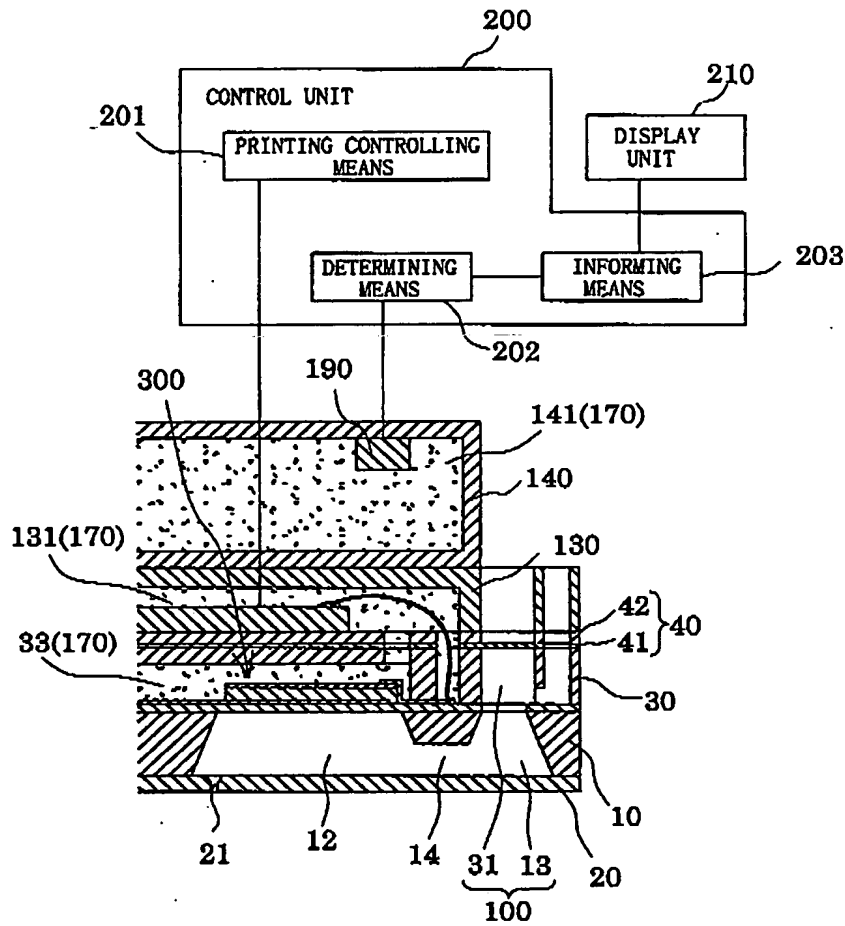


FIG. 7

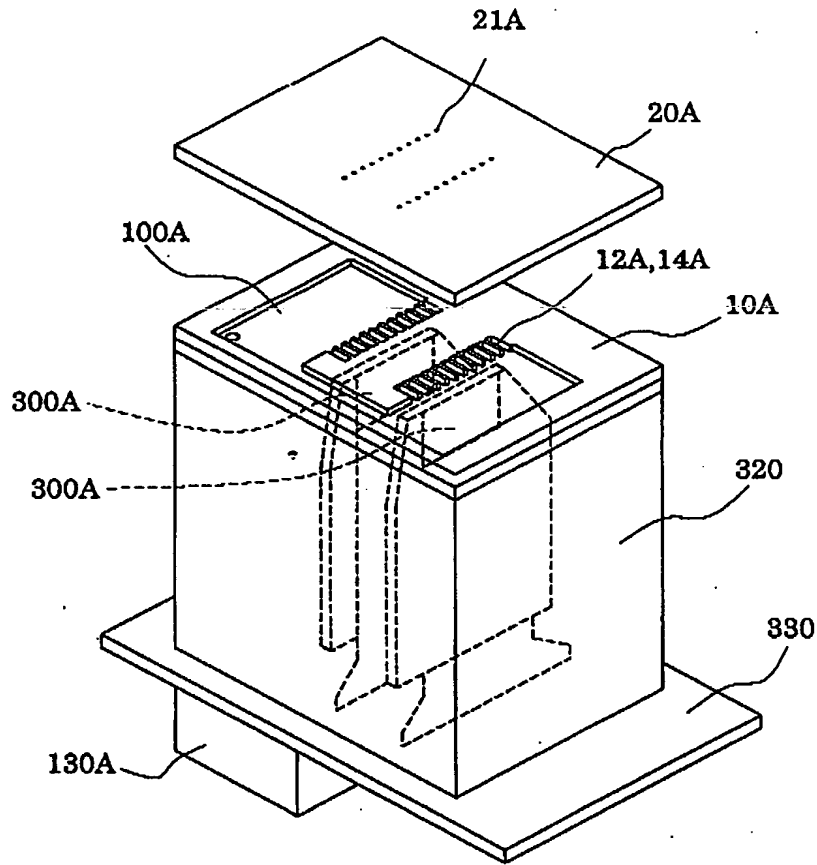


FIG.8

